

CLAIM AMENDMENTS:

Claims 1-36 (canceled).

Claim 37 (currently amended): A composite laminated substrate for integrated and minimized electronic circuits, comprising:

an inorganic substrate having at least one passive component embedded therein; and an organic substrate which is laminated to one side of the inorganic substrate and which has circuits for electrical connections ~~between outer input/output ports and to~~ the at least one passive component of the inorganic substrate.

wherein the organic substrate is composed of a plurality of printed circuit boards.

Claim 38 (previously presented): The composite laminated substrate according to claim 37, wherein the inorganic substrate is comprised of a material selected from the group consisting of ceramic, silicon and glass.

Claim 39 (previously presented): The composite laminated substrate according to claim 38, wherein the material of the inorganic substrate is ceramic and wherein the at least one passive component is one of a thick film passive component or a thin film passive component.

Claim 40 (previously presented): The composite laminated substrate according to claim 38, wherein the material of the inorganic substrate is silicon and wherein the at least one passive component is a semiconductor-fabricated passive component.

Claim 41 (previously presented): The composite laminated substrate according to claim 37, wherein the at least one passive component is selected from the group consisting of a capacitor, an inductor, a resistor, and any mixture thereof.

Claim 42 (Cancelled)

Claim 43 (previously presented): The composite laminated substrate according to claim 42, wherein the plurality of printed circuit boards are stacked, with each having its own respective separate circuitry.

Claim 44 (currently amended): The composite laminated substrate according to claim 43, wherein the organic substrate has an outer surface layer which is a built-up surface layer, wherein the outer surface layer which includes a circuit.

Claim 45 (currently amended): The composite laminated substrate according to claim 37, wherein the organic substrate further comprises at least one further passive component.

Claim 46 (currently amended): The composite laminated substrate according to claim 45, wherein the at least one further passive component of the organic substrate is selected from the group consisting of a capacitor, an inductor, a resistor, and any mixture thereof.

Claim 47 (previously presented): The composite laminated substrate according to claim 37, wherein the organic substrate is a built-up organic substrate provided on the inorganic substrate.

Claim 48 (previously presented): The composite laminated substrate according to claim 37, further comprising a bonding layer which is provided between the inorganic substrate and the organic substrate, and which bonds together the inorganic substrate and the organic substrate.

Claim 49 (currently amended): A composite laminated substrate for integrated and minimized electronic circuits, comprising:

an inorganic substrate having at least one passive component formed thereon or embedded therein; and

two organic substrates which are laminated to respective sides of the inorganic substrate and integrated therewith, and which have circuits for electrical connections ~~between outer input/output ports and to~~ the at least one passive component of the inorganic substrate ~~through the two organic substrates;~~

wherein each of the two organic substrates is composed of a plurality of printed circuit boards.

Claim 50 (previously presented): The composite laminated substrate according to claim 49, wherein the inorganic substrate is comprised of a material selected from the group consisting of ceramic, silicon and glass.

Claim 51 (previously presented): The composite laminated substrate according to claim 50, wherein the material of the inorganic substrate is ceramic and wherein the at least one passive component is one of a thick film passive component or a thin film passive component.

Claim 52 (previously presented): The composite laminated substrate according to claim 50, wherein the material of the inorganic substrate is silicon and wherein the at least one passive component is a semiconductor-fabricated passive component.

Claim 53 (previously presented): The composite laminated substrate according to claim 49, wherein the passive component is selected from the group consisting of a capacitor, an inductor and a resistor.

Claim 54 (Cancelled).

Claim 55 (currently amended): The composite laminated substrate according to claim 49, wherein ~~each of the two organic substrates is composed of~~ a plurality of printed circuit boards which of each respective organic substrate are stacked ~~respectively~~, and wherein each printed circuit board of each respective plurality of printed circuit boards has its own respective separate circuitry.

Claim 56 (previously presented): The composite laminated substrate according to claim 55, wherein each of the two organic substrates has an outer surface layer which is a built-up surface layer, wherein the outer surface layer ~~which~~ includes a circuit.

Claim 57 (previously presented): The composite laminated substrate according to claim 49, wherein at least one of the two organic substrates further comprises at least one passive component.

Claim 58 (previously presented): The composite laminated substrate according to claim 57, wherein the at least one passive component of the at least one of the two organic substrates is selected from the group consisting of a capacitor, an inductor, a resistor, and any mixture thereof.

Claim 59 (previously presented): The composite laminated substrate according to claim 49, wherein at least one of the two organic substrates is a built-up organic substrate provided on the inorganic substrate.

Claim 60 (currently amended): The composite laminated substrate according to claim 49, further comprising a covering layer which is provided on the inorganic substrate and covers the inorganic substrate, which integrates the inorganic substrate with one of the two organic substrates, and which comprises circuits for providing electrical connections between the at least one passive component of the inorganic substrate and said one of the two organic substrates, wherein the top and bottom of the inorganic substrate ~~[[is]]~~are fully covered by said two organic substrates.

Claim 61 (previously presented): The composite laminated substrate according to claim 49, further comprising a bonding layer which is provided between the inorganic substrate and at least one of the two organic substrates,

and which bonds together the inorganic substrate and said at least one of the two organic substrates.

Claim 62 (previously presented): The composite laminated substrate according to claim 49, wherein the at least one passive component is separated from, so as to not directly contact, the two organic substrates.

Claim 63 (previously presented): The composite laminated substrate according to claim 37, wherein the at least one passive component is separated from, so as to not directly contact, the organic substrate.